



PRODUCT DATASHEET



- DC Input Photo Coupler
- Random-Phase TRIAC

TD302X(SL)(T1)-GV(W)





APPLICATIONS:

- Solenoid/valve controls •
- Lighting controls
- Motor controls •
- **Temperature controls** .
- Static AC power switches
- Solid state relays •
- Interfacing microprocessors to 115 • to 240VAC peripherals

TD302X(SL)(W) Series

DESCRIPTION:

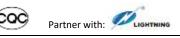


The TD302X(SL)(W) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP6 package with SMD6 Low Profile lead forming option.

With the robust coplanar double mold structure, TD302X(SL) (W) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- **REACH & RoHS compliance**
- MSL class 1
- **Regulatory Approvals:**
 - UL UL1577 0
 - VDE EN60747-5-5 (VDE0884-5) 0
 - CQC GB4943.1, GB8898 0
 - cUL CSA Component Acceptance Service Notice 5A 0
- Packing: 1000pcs/reel 6 RI RI (4



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Naming Information:

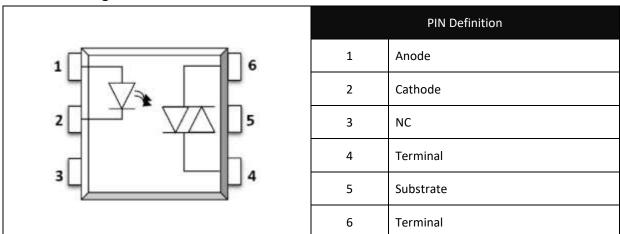
TD302 X (SL) (T1) - G V (W)				
TD302X	Part Number			
×	Selection: LED Trigger Current (X=1~3)			
SL	Lead Form Option: SMD6 Low Profile			
T1	Selection: Tape and Reel Option (T1(default)/T2)			
G	Green Option			
V	VDE Option			
W	White Package			

Ordering Information:

TD302 <mark>X</mark> (SL)(T1)-GV(W)								
<u>X</u> = Selection: LED Trigger Current (X=1~3)								
Part Number	Symbol	Symbol Values			Unit	Test Condition		
	Symbol	Symbol	Symbol	Min.	Тур.	Max.	Onne	
TD3021(SL)(T1)-GV(W)				15		L =100m A		
TD3022(SL)(T1)-GV(W)	I _{FT}			10	mA	I™=100mA Terminal		
TD3023(SL)(T1)-GV(W)				5		Voltage=3V		

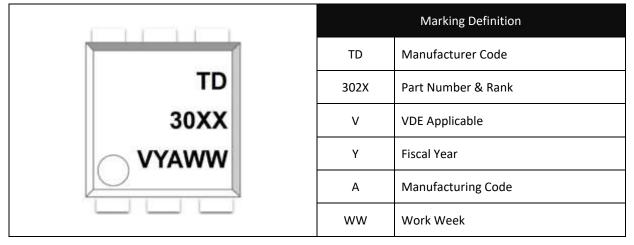
Version No.	Original Release Date
Rev: A01	21/06/2021





Schematic Diagram:

Marking Information:



Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	lF	60	mA			
Reverse Voltage	VR	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
	OUTPUT					
Off-State Output Terminal Voltage	Vdrm	400	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітѕм	1	А			
On-State RMS Current	I _{T(RMS)}	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	Viso	5000 ^{*1}	Vrms			
Operating Temperature	T _{opr}	-40~+100	°C			
Storage Temperature	T _{stg}	-55~+125	°C			
Soldering Temperature	T _{sol}	260 ^{*2}	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

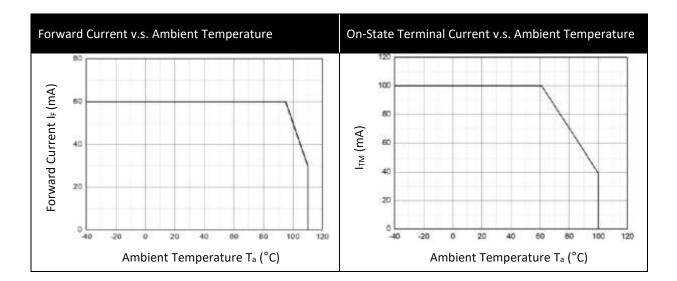
Electrical Optical	Characteristics at T _a =25°C:
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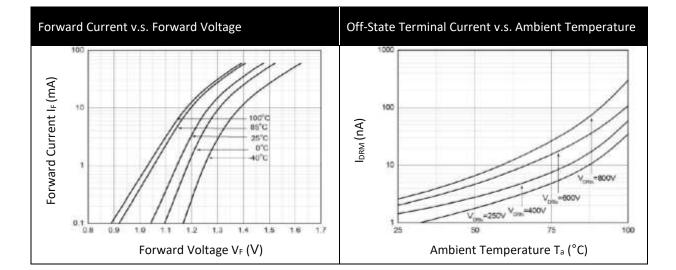
Parameter		Symbol	Min	Values	Max	Unit	Test Condition
INPUT							
Forward Voltage		V _F		1.24	1.4	V	I _F =10mA
Reverse Current		I _R			10	μΑ	V _R =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
	OUTPUT						
Peak Off-State Curren Either Direction	nt	Idrm			100 *1	nA	V_{DRM} =Rated V_{DRM} I _F =0
Peak On-State Voltag Either Direction	je	V _{TM}		1.58	2.5	v	I _{TM} =100mA
Critical Rate of Rise of Voltage	f Off-State	dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
		TRAM	NSFER CHAR	ACTERISTICS			
LED Trigger Current TI	TD3021				15		100m4
	TD3022	I _{FT}			10	mA	I™=100mA Terminal Voltage=3V
	TD3023				5		voitage=3v
Holding Current		Ін		257		μΑ	
Isolation Resistance R _{ISO}		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.8		pF	V=0, f=1MHz

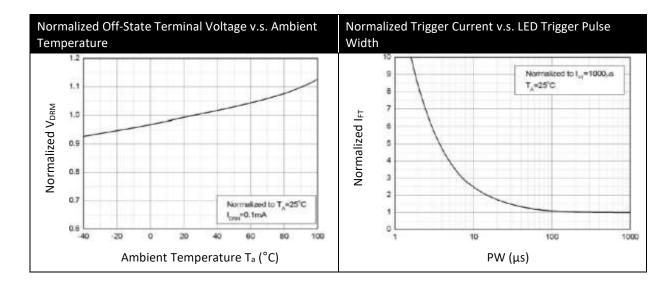
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

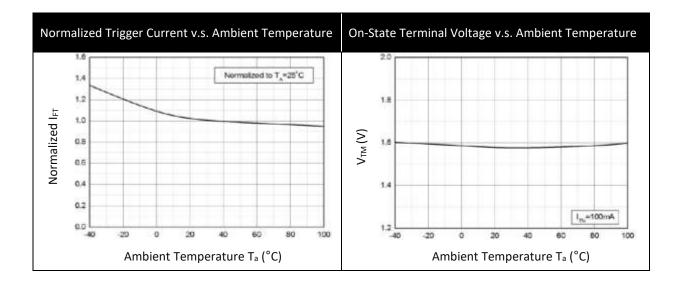


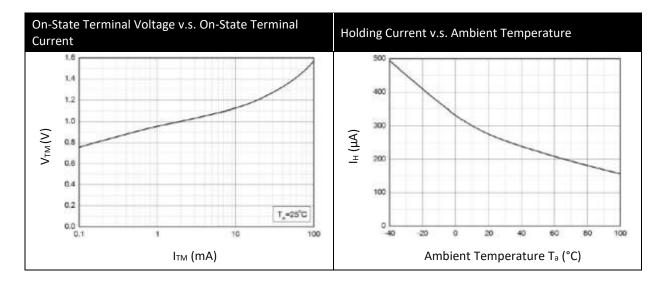


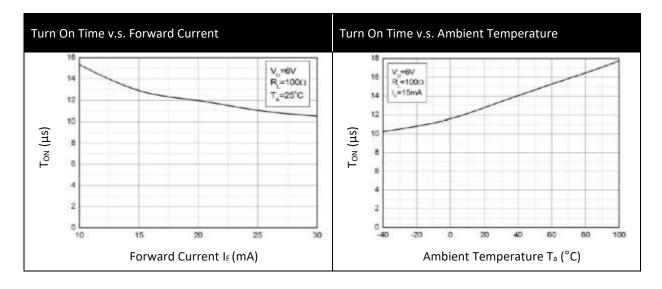




CHARACTERISTIC CURVES:

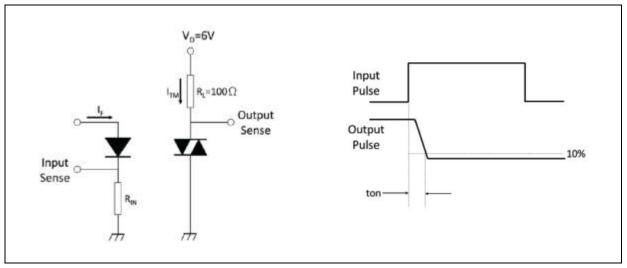






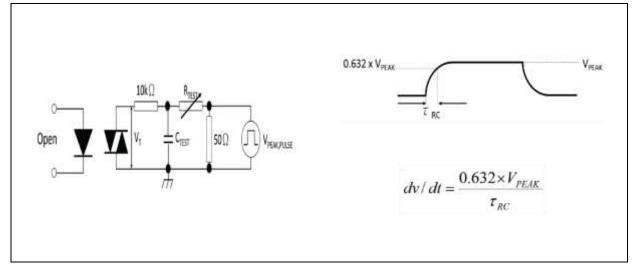


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

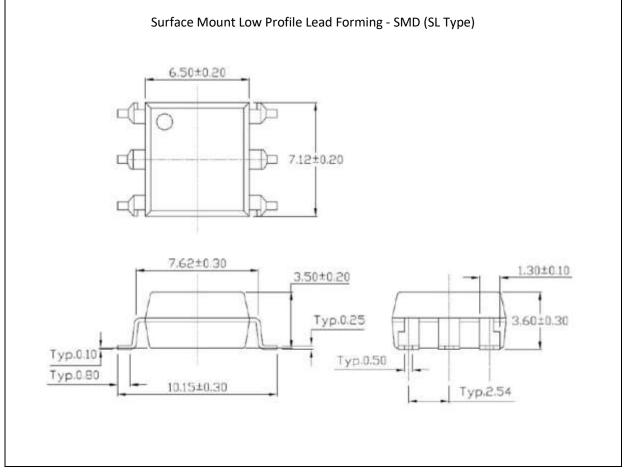
Test Circuit and Waveforms of dV/dt:





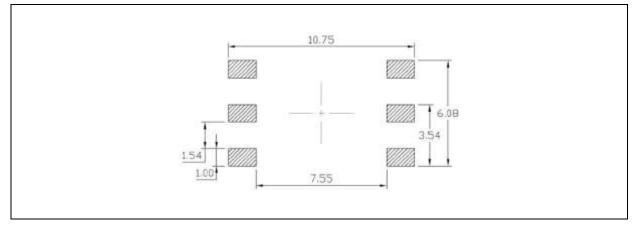
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

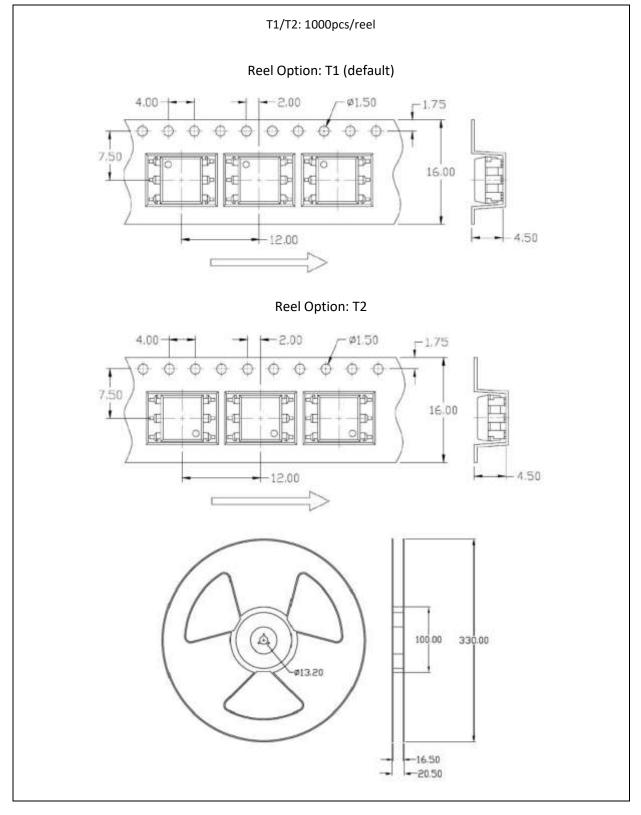
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).



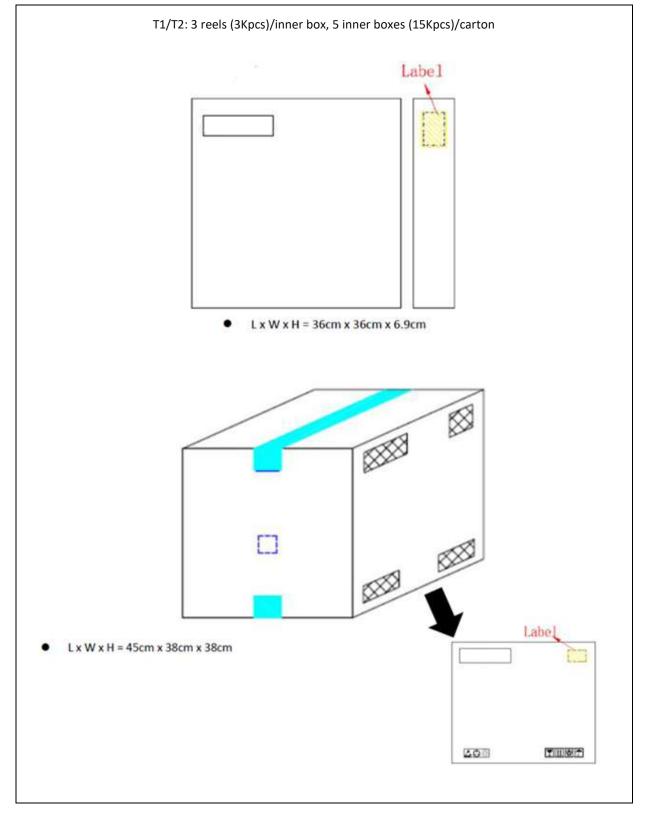
Reel Dimension:





PACKING SPECIFICATION:

Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

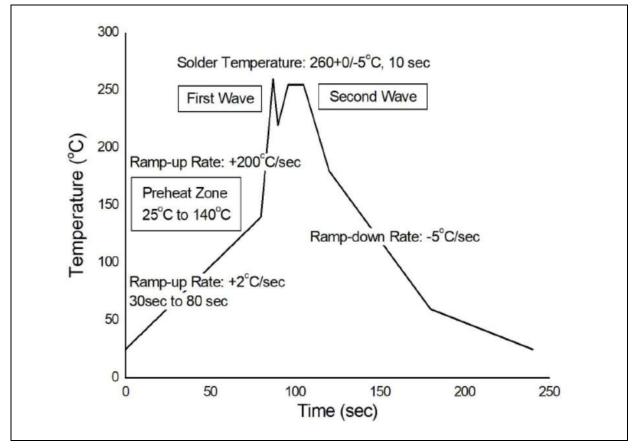
Γ

Supplier T _p 2		er $T_p \leq T_c$
	,	t _p → +-T _c -5°C
	Time ⇒	1 PC-02
Profile Feature		۲۰۰۵ Pb-Free Assembly Profile
	Time ⇔	
Profile Feature	Time → Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Profile Feature Temperature Min. (T _{smin})	Time → Sn-Pb Assembly Profile 100°C	Pb-Free Assembly Profile 150°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C	Pb-Free Assembly Profile 150°C 200°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max.	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max.
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)	Time Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)Peak Body Package Temperature	Time Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.